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(54) **Title:** LOWER IC PACKAGE STRUCTURE FOR COUPLING WITH AN UPPER IC PACKAGE TO FORM A PACKAGE-ON-PACKAGE (POP) ASSEMBLY AND POP ASSEMBLY INCLUDING SUCH A LOWER IC PACKAGE STRUCTURE

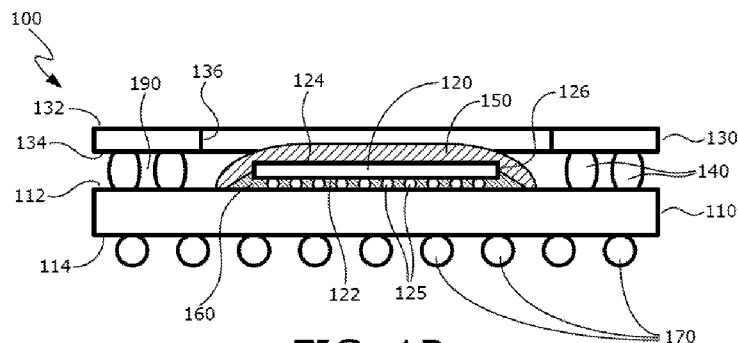


FIG. 1B

(57) **Abstract:** Disclosed are embodiments of a lower integrated circuit (IC) package structure for a package-on-package (PoP) assembly. The lower IC package structure includes an interposer having pads to mate with terminals of an upper IC package. An encapsulant material is disposed in the lower IC package, and this encapsulant may be disposed proximate one or more IC die. An upper IC package may be coupled with the lower IC package to form a PoP assembly. Such a PoP assembly may be disposed on a mainboard or other circuit board, and may form part of a computing system. Other embodiments are described and claimed.